Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	"361"/$.ccls. and spacer with circuit adj board with (land pad terminal) and weld$3 and plat$3	USPAT; EPO; JPO	OR	ON	2004/12/07 12:31
L2	1	"174"/$.ccls. and spacer with circuit adj board with (land pad terminal) and weld$3 and plat$3	USPAT; EPO; JPO	OR	ON	2004/12/07 12:31
L3	0	"29"/$.ccls. and spacer with circuit adj board with (land pad terminal) and weld$3 and plat$3	USPAT; EPO; JPO	OR	ON	2004/12/07 12:32
L4	4	"257"/$.ccls. and spacer with circuit adj board with (land pad terminal) and weld$3 and plat$3	USPAT; EPO; JPO	OR	ON	2004/12/07 12:33
L5	16	"257"/$.ccls. and (core spacer) with circuit adj board with (land pad terminal) and (inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:36
L6	5	"29"/$.ccls. and (core spacer) with circuit adj board with (land pad terminal) and (inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:37
L7	13	"174"/$.ccls. and (core spacer) with circuit adj board with (land pad terminal) and (inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:38
L8	15	"361"/$.ccls. and (core spacer) with circuit adj board with (land pad terminal) and (inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:38
L9	58	"361"/$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (encapsulat$3 inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:42
L10	61	"174"/$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (encapsulat$3 inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:44
L11	50	"29"/$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (encapsulat$3 inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:45
L12	87	"361"/$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (deposit$3 cur$3 encapsulat$3 inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:51

L13	38	("4813129").URPN.	USPAT	OR	ON	2004/12/07 12:49
L14	94	"361"/$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (core spacer) with (weld$3 plat$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:55
L15	94	"29"/$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (core spacer) with (weld$3 plat$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:31
L16	0	"29"/$.ccls. and spacer with (substrate board) with (land pad terminal) and control$3 near3 collaps$3 near3 chip near3 connect$3 with (weld$3 plat$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:32
L17	0	spacer with (substrate board) with (land pad terminal) and control$3 near3 collaps$3 near3 chip near3 connect$3 with (weld$3 plat$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:33
L18	0	spacer with (land pad terminal) and control$3 near3 collaps$3 near3 chip near3 connect$3 with (weld$3 plat$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:33
L19	2	spacer with (land pad terminal) and control$3 near3 collaps$3 near3 chip near3 connect$3 same (weld$3 plat$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:33
L20	6	spacer with (land pad terminal) same (weld$3 plat$3) and control$3 near3 collaps$3 near3 chip near3 connect$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:34
L21	92	spacer with (land pad terminal) same (weld$3 plat$3) and ("4c" "4-c")	USPAT; EPO; JPO	OR	ON	2004/12/07 15:37
L22	9	"361"/$.ccls. and spacer near3 plat$3 with (land pad terminal) and (deposit$3 insert$3 inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:40
L23	27	"361"/$.ccls. and spacer with (land pad terminal) same (board substrate) and spacer near3 plat$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:42
L24	0	"361"/$.ccls. and spacer with (land pad terminal) same (board substrate) and spacer near3 weld$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:42
L25	234	spacer with (land pad terminal) same (board substrate) and spacer near4 (plat$3 weld$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 17:06
L26	113	spacer with (land pad terminal) same (board substrate) and spacer near4 (plat$3 weld$3) with (land pad terminal)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:56

L28	731	spacer with (land pad terminal) same (board substrate) and (deposit$3 insert$3 inject$3 fill$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:56
L29	17	spacer with (land pad terminal) same (board substrate) and (deposit$3 insert$3 inject$3 fill$3) with (epoxy insulat$3 dielectric) and partial$2 near3 cur$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:58
L30	45	spacer with (land pad terminal) same (board substrate) and (deposit$3 insert$3 inject$3 fill$3) with (epoxy insulat$3 dielectric) same cur$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:59
L31	31	("5037312").URPN.	USPAT	OR	ON	2004/12/07 17:18
L32	15	29/$.ccls. and spacer with (land pad terminal) same (board substrate) and spacer near4 (plat$3 weld$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 17:08
L33	43	29/$.ccls. and spacer with (land pad terminal) same (board substrate) and solder	USPAT; EPO; JPO	OR	ON	2004/12/07 17:08
L34	116	361/758.CCLS.	USPAT	OR	ON	2004/12/07 17:18
S1	4	sundahl.in. and interconnect$.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2004/11/30 10:26
S2	23	("4693770"|"4818728"|"5233504"|"5311059"|"5583350"|"5659203"|"5703394"|"5722161"|"5726502"|"5764485"|"5767580"|"5795818"|"5801446"|"5838069"|"5858806"|"5861678"|"5889568"|"5907187"|"5912505"|"5987358"|"6018197"|"6040631"|"6324754").PN.	USPAT; EPO; JPO	OR	ON	2004/12/03 16:41
S3	2	LED same spacer same glass near3 (substrate board) and (ceramic printed) near3 board	USPAT; EPO; JPO	OR	ON	2004/12/03 16:53
S4	58	display same spacer same glass near3 (substrate board) and (ceramic printed) near3 board	USPAT; EPO; JPO	OR	ON	2004/12/03 17:01
S5	28	display and spacer same electrode and glass near3 (substrate board) and (ceramic printed) near3 board and (opto$1electric$3 processor)	USPAT; EPO; JPO	OR	ON	2004/12/03 17:56
S6	42	(lcd led) and align$3 same (spacer core spherical) with member and (glass ceramic) with (substrate board)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:35

S7	59	align$3 same (spacer core spherical) with member and (glass ceramic) with (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:40
S8	470	align$3 same spacer and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:41
S9	21	align$3 same spacer with (terminal pad land) and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:47
S10	4	align$3 same spacer with (terminal pad land) and glass near3 (substrate board) same ceramic near3 (substrate board)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:45
S11	11	align$3 same spacer with (terminal pad land) and glass near3 (substrate board) and ceramic near3 (substrate board)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:45
S12	12	("5136365" | "5187020" | "5375042" | "5412539" | "5509200" | "5518674" | "5805426" | "5893765" | "5905638" | "5910641" | "6090633" | "6326561").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:46
S13	9	align$3 same core with (terminal pad land) and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:55
S14	7	("5108027" | "5431328" | "5838069" | "5971253" | "6087597" | "6278184" | "6337445").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:48
S15	3	("5431328" | "5868304" | "5956235").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:50
S16	21	("3089062" | "3331912" | "3392442" | "4020987" | "4640438" | "4746583" | "5153709" | "5268815" | "5294830" | "5324892" | "5329160" | "5372295" | "5414300" | "5471027" | "5517753" | "5523260" | "5551627" | "5881945").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:51

S17	31	("4001870" | "4365264" | "4538105" | "4618878" | "4695870" | "4716049" | "4792532" | "4813129" | "4902606" | "4994735" | "5020219" | "5070297" | "5072520" | "5103557" | "5120665" | "5135890" | "5148265" | "5148266" | "5153507" | "5180311" | "5321583" | "5393697" | "5430329" | "5431328" | "5440241" | "5455390" | "5578527" | "5604380" | "5666270" | "5679977" | "5749997").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:52
S18	12	("3401126" | "3809625" | "4402450" | "4705205" | "4749120" | "4903889" | "4916523" | "4963002" | "5134460" | "5329423").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:54
S19	6	align$3 same spherical with (terminal pad land) and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:56
S20	44	align$3 same solder near2 ball with (terminal pad land) and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 18:46
S21	5	align$3 same solder near2 ball with (terminal pad land) and (glass ceramic) near3 (substrate board) and injecting with (epoxy insulat$3 dielectric) same curing	USPAT; EPO; JPO	OR	ON	2004/12/06 18:48
S22	5	align$3 same solder near2 ball with (terminal pad land) and (glass ceramic) near3 (substrate board) and injecting with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/06 18:48
S23	0	align$3 same spacer with (terminal pad land) and (glass ceramic) near3 (substrate board) and injecting with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/06 18:48
S24	8	align$3 same spacer with (terminal pad land) and (glass ceramic) near3 (substrate board) and (fill$3 inject$3) with (epoxy insulat$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/06 18:49
S25	15	("4617730" | "4954878" | "5010038" | "5086558" | "5218234" | "5426072" | "5447264" | "5468681" | "5504035" | "5817541" | "5821624" | "5866949" | "5915169" | "6020220" | "6242815").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 18:49